STACKED MICROELECTRONIC ASSEMBLY WITH MICROELECTRONIC ELEMENTS HAVING VIAS EXTENDING THROUGH BOND PADS

Abstract: A stacked microelectronic assembly is provided which includes first and second stacked microelectronic elements (101, 102). Each of the first and second microelectronic elements can include a conductive layer (610) extending along a face (608) of such microelectronic element. At least one of the first and second microelectronic elements can include a recess (618) extending from the rear surface towards the front surface, and a conductive via (605) extending from the recess through the bond pad (603) and electrically connected to the bond pad, with a conductive layer (610) connected to the via and extending along a rear face (608) of the microelectronic element (101, 102) towards an edge (620) of the microelectronic element. A plurality of leads (224) can extend from the conductive layers (610) of the first and second microelectronic elements and a plurality of terminals (616) of the assembly can be electrically connected with the leads.
TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

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